

IN THE ABSTRACT:

Please amend the abstract as follows:

~~The present invention relates to a~~ A method and an arrangement for a testing of substrates (1) provided with a predetermined pattern, in particular circuit boards with an application of solder paste. In accordance with the ~~present~~ invention the actual pattern (1a) applied to the substrate by means of a printing or structuring process (3, 4) is optically detected, the optically detected actual pattern is compared with a desired pattern and in dependence on the comparison and taking into account permissible tolerances it is determined to which further process the observed substrate provided with the actual pattern is to be delivered, wherein the optical detection of the actual pattern is effected in the form of digital data with the formation of an actual data set, a desired data set is formatted from control data for the application of the pattern to the substrates, and data processing is carried out to the effect that the desired data set and the actual data set are compared datawise with one another taking into account permissible tolerances.

[Fig. 1]